Memory Devices

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Outline

- Introduction
- Memory Organization
- Memory Characteristics
- Access mechanisms
- Where we are coming from
- External vs Internal Architectures
- Memory Hierarchy
- Memories with ECCs

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Computer Memories



Physical devices used to store programs and data on a temporary or permanent basis in digital systems

Memory organization

- Memories are composed of cells (each cell stores 1 bit)
- Cells are organized in words
- From the user viewpoint, a word is the information quantum that can be exchanged with the memory

Memory operations

- On each word, data can be
 - Written
 - Read



• Memories are the only sequential devices without a reset signal

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Cell Size (F²)

F = feature size = half the distance between like points in an array of minimum width and minimum spaced metal1

Memories Today

	SRAM	DRAM	NOR-Flash	NAND-Flash
Cell Size	120F ²	4-6F ²	10 F ²	4-5 F ²
Read Latency	<1ns	20ns	5,000ns	25,000ns
Write Latency	<1ns	20ns	1,000,000ns	200,000ns
Static power	YES	YES	NO	NO
Endurance	> 10 ¹⁵	> 10 ¹⁵	10 ⁴	10 ⁴
Non-volatility	NO	NO	YES	YES

Cell Size (F²)
Scalability

The maximum extent to which the Cell Size can be shrunk

- Cell Size (F²)
- Scalability
- Access Time

The time required to perform a read or a write operation

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- Cell Size (F²)
- Scalability
- Access Time
- Power Consumption

- Cell Size (F²)
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- Endurance

The number of cycles the memory operates correctly

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Write Latency	<1ns	20ns	1,000,000ns	200,000ns
Static power	YES	YES	NO	NO
Endurance	> 10 ¹⁵	> 10 ¹⁵	10 ⁴	104
Non-volatility	NO	NO	YES	YES

- Cell Size (F²)
- Scalability
- Access Time
- Power Consumption
- Endurance
- Data Reliability

The ability to preserve data under disturbances

- Cell Size (F²)
- Scalability
- Access Time
- Power Consumption
- Endurance
- Data Reliability
- Volatility

The ability to preserve data when power is removed

Memories Today

SRAM	DRAM	NOR-Flash	NAND-Flash
120F ²	4-6F ²	10 F ²	4-5 F ²
<1ns	20ns	5,000ns	25,000ns
<1ns	20ns	1,000,000ns	200,000ns
YES	YES	NO	NO
> 10 ¹⁵	> 10 ¹⁵	10 ⁴	10 ⁴
NO	NO	YES	YES
	SRAM 120F ² <1ns <1ns YES >10 ¹⁵	SRAM DRAM 120F ² 4-6F ² <1ns 20ns <1ns 20ns ×1ns 20ns ×1ns 20ns ×10 ¹⁵ >10 ¹⁵ NO NO	SRAM DRAM NOR-Flash $120F^2$ $4-6F^2$ $10F^2$ $<1ns$ $20ns$ $5,000ns$ $<1ns$ $20ns$ $1,000,000ns$ $<1ns$ $20ns$ $1,000,000ns$ YES YES NO $>10^{15}$ $>10^{15}$ 10^4 NO NO YES

- Cell Size (F²)
- Scalability
- Access Time
- Power Consumption
- Endurance
- Data Reliability
- Volatility
- Fabrication Cost

- Cell Size (F²)
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Access Mechanisms

- Data Access:
 - By address
 - By content:
 - CAM (Content Addressable Memories)
 - Associative Memories
 - By writing order: FIFO (First-In First-Out)

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Access by Address

- Each word can be accessed independently and is univocally identified by an *Address*
- On each word, data can be
 - Written
 - Read



Timing diagram for a read operation



Timing diagram for a write operation



D_out during write operation

- Advanced memory supports three forms of write behavior:
 - Normal Data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output.
 - Write Through A copy of the input data appears at the output of the same port.
 - Read-Before-Write When new data is being written, the old contents of the address appears at the output.

Dual port RAM

- Synchronous Read and Write Access
- Separate clock control of A and B ports
- Word Write
- Fully Synchronous independent operation from each port

Dual port RAM: symbol



Dual port RAM: sym Write Enable for port A





Dual port RAM: Principle of operation

- Simultaneously accessing the same memory location with same clock rate may result in the following:
 - Both ports writing: unknown data will be written
 - One port writing, other port reading: Write is completed, while the data read out is technology dependent.
Access Mechanisms

- Data Access:
 - By address
 - By content:
 - CAM (Content Addressable Memories)
 - Ternary CAM
 - Associative Memories
 - By writing order: FIFO (First-In First-Out

Content Addressable Memories

- A CAM gets in input a data (of the same size of the CAM words) and provides in output the address of the word whose content equals the input data
 - In case of multiple matches, the minum (or maximum) address is provided
 - In case of missmatch (the input data is not stored in the CAM), a status signal is asserted

CAM conceptual view











Access Mechanisms

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TCAM (Ternary CAM)

- A variation of CAM in which don't care values can be used during the search
- Conceptually, in a TCAM cell, one can store the value "-", that during search will match with both "0" and "1"





Access Mechanisms

- Data Access:
 - By address

- By content:

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Associative memories

- Sistemi principalmente costituiti da memorie di tipologia CAM più della logica sparsa e talvolta reti neurali
- Utilizzati per ricerche nelle quali il matching avvenga anche in caso di un certo grado di "similitudine" tra la stringa cercata e quella memorizzata nella memoria (e.g., Christophoro Columbus potrebbe essere riconosciuto come Cristoforo Colombo).

Access Mechanisms

- Data Access:
 - By address

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- By writing order: FIFO (First-In First-Out)



- Functionally equivalent to the homonymous wellknown Abstract Data Type defined in CS
- Usually implemented resorting to dual port RAMs

FIFO memories

 Mostly used as interface buffers between producers and consumers with different throughputs



FIFO Cypress CY7C42x5



Lecture 0_7.5 - Slide 50

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Data Storage Evolution



Memory Evolution



Memory Evolution



CMOS Technology Evolution



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Technology Scaling Effects

ADVANTAGES	ISSUES
Higher integration Higher speed Lower capacitance	Higher variability Decreased dependability Increased leakage power
Lower switching energy	CPU vs. Memory

CPU vs. Memory



[Hennessy and Patterson, 5th Edition]

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External vs Internal Architectures

When dealing with a memory component, one must distinguish between

- **External architecture** : the way a user "sees" the components and can use it
- Internal architecture : how cells are actually organized within the component.

An example: the Micron MT48LC32M16A2 Memory

A Synchronous Memory of 512 Mb, accessible from a user as a memory of 32 M words of 16 bits, each.

- External architecture :
 - Address bus of 15 bits to access each of the 32 M (=2¹⁵) words
 - Data bus of 16 bit
 - Several control and status signals
- Internal architecture :
 - 4 banks (or matrices, or arrays), each composed of 8 k rows and 1 k columns, each column including 16 bits.



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Memory Hierarchy



Memory Hierarchy



Memory Hierarchy



Where are we going Architecture



Where are we going Architecture

- Reconfiguration:
 - Service-Oriented:
 - User Selectable
 - Application Driven
 - Aging-Dependent



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Memories with Error Correction Capability

 Memories are mostly equipped with EDACs (Error Detectors and Correctors), all exploiting ECCs (Error Correcting Codes)

An example of information redundancy
















- Codes (parity, Hamming, Berger, Solomon, cyclic, arithmetic, ...) are classified according to their ability to detect and correct errors affecting the code words:
 - k-error detecting code: detect the presence of an error that modifies up to k bits
 - k-error correcting code: correct an error that modifies up to k bits.

Hamming Codes

- Being N the word size, they require log₂ N bits of code and are able to:
 - Correct ALL Single Errors
 - Detect ALL Double Errors
- Thus, are often referred to as SEC-DED Code (Single Error Correction Double Error Detection).

